

## SNx4AC14 Hex Schmitt-Trigger Inverters

### 1 Features

- $V_{CC}$  operation of 2V to 6V
- Inputs accept voltages to 6V
- Max  $t_{pd}$  of 9.5ns at 5V

### 2 Applications

- [Synchronize inverted clock inputs](#)
- [Debounce a switch](#)
- Invert a digital signal

### 3 Description

These Schmitt-trigger devices contain six independent inverters.

#### Device Information

PART NUMBER	PACKAGE <sup>(1)</sup>	PACKAGE SIZE <sup>(2)</sup>	BODY SIZE <sup>(3)</sup>
SNx4AC14	BQA (WQFN, 14)	3.00mm × 2.50mm	3.00mm × 2.50mm
	D (SOIC, 14)	8.65mm × 6mm	8.65mm × 3.9mm
	DB (SSOP, 14)	6.2mm × 7.8mm	6.2mm × 5.3mm
	N (PDIP, 14)	19.3mm × 9.4mm	19.3mm × 6.35mm
	NS (SOP, 14)	10.2mm × 7.8mm	10.3mm × 5.3mm
	PW (TSSOP, 14)	5mm × 6.4mm	5mm × 4.4mm

- (1) For more information, see [Section 11](#).
- (2) The package size (length × width) is a nominal value and includes pins, where applicable.
- (3) The body size (length × width) is a nominal value and does not include pins.



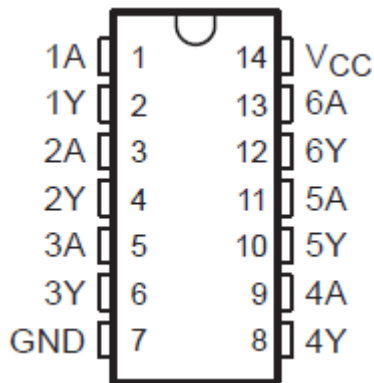
Logic Diagram (Positive Logic)



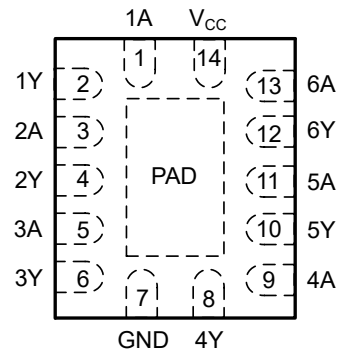
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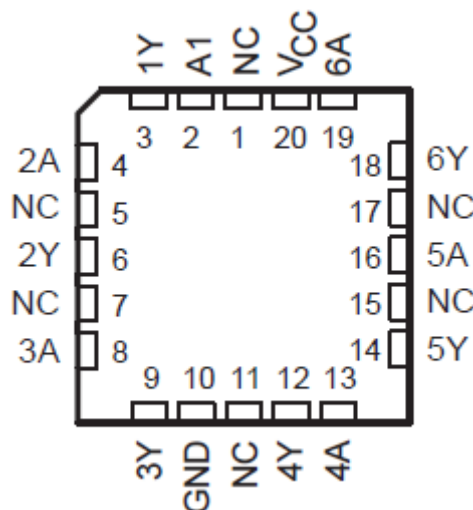
## 4 Pin Configuration and Functions



**Figure 4-1. SN54AC14 J or W Package; SN74AC14 D, DB, N, NS, or PW Package; 14-Pin CDIP, CFP, SSOP, SOIC, PDIP, SOP, or TSSOP (Top View)**



**Figure 4-2. SN54AC14 BQA Package, 14-Pin WQFN (Top View)**



NC – No internal connection

**Figure 4-3. SN54AC14 FK Package, 20-Pin LCCC (Top View)**

**Table 4-1. Pin Functions**

NAME	PIN		I/O	DESCRIPTION
	D, DB, N, NS, PW, BQA, J, or W	FK		
1A	1	2	Input	Channel 1, Input A
1Y	2	3	Output	Channel 1, Output Y
2A	3	4	Input	Channel 2, Input A
2Y	4	6	Output	Channel 2, Output Y
3A	5	8	Input	Channel 3, Input A
3Y	6	9	Output	Channel 3, Output Y
GND	7	10	—	Ground
4Y	8	12	Output	Channel 4, Output Y
4A	9	13	Input	Channel 4, Input A

**Table 4-1. Pin Functions (continued)**

NAME	PIN		I/O	DESCRIPTION
	D, DB, N, NS, PW, BQA, J, or W	FK		
5Y	10	14	Output	Channel 5, Output Y
5A	11	16	Input	Channel 5, Input A
6Y	12	18	Output	Channel 6, Output Y
6A	13	19	Input	Channel 6, Input A
V <sub>CC</sub>	14	20	—	Positive Supply
NC		1, 5, 7, 11, 15, 17	—	Not internally connected
Thermal Pad <sup>(1)</sup>			—	The thermal pad can be connected to GND or left floating. Do not connect to any other signal or supply.

(1) BQA package only.

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted<sup>(1)</sup>)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range		-0.5V	7	V
V <sub>I</sub> <sup>(2)</sup>	Input voltage range		-0.5V	V <sub>CC</sub> + 0.5	V
V <sub>O</sub> <sup>(2)</sup>	Output voltage range		-0.5V	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	(V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub> )		±20	mA
I <sub>OK</sub>	Output clamp current	(V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )		±20	mA
I <sub>O</sub>	Continuous output current	(V <sub>O</sub> = 0 to V <sub>CC</sub> )		±50	mA
	Continuous current through V <sub>CC</sub> or GND			±200	mA
T <sub>stg</sub>	Storage temperature range		-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 5.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	±4000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	±2000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 5.3 Recommend Operating Conditions

		SN54AC14		SN74AC14		UNIT
		MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage	2	6	2	6	V
V <sub>I</sub>	Input voltage	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 3 V		-12	-12	mA
		V <sub>CC</sub> = 4.5 V		-24	-24	
		V <sub>CC</sub> = 5.5 V		-24	-24	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 3 V		12	12	mA
		V <sub>CC</sub> = 4.5 V		24	24	
		V <sub>CC</sub> = 5.5 V		24	24	
T <sub>A</sub>	Operating free-air temperature	-55	125	-40	85	°C

### 5.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		SN74AC14						UNIT
		BQA (WQFN)	D (SOIC)	DB (SSOP)	N (PDIP)	NS (SO)	PW (TSSOP)	
		14 PINS						
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	93.4	89.9	96	72.1	92.4	148	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54AC14		SN74AC14		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>T+</sub> Positive-going threshold		3 V	0.8	1.8	2.2	0.8	2.2	0.8	2.2	V
		4.5 V	1.5	2.6	3.2	1.5	3.2	1.5	3.2	
		5.5 V	1.6	3.2	3.9	1.6	3.9	1.6	3.9	
V <sub>T-</sub> Negative-going threshold		3 V	0.5	0.8	1	0.5	1.2	0.5	1	V
		4.5 V	0.9	1.4	1.8	0.9	1.8	0.9	1.8	
		5.5 V	1.1	1.8	2.3	1.1	2.3	1.1	2.3	
ΔV <sub>T</sub> Hysteresis (V <sub>T+</sub> - V <sub>T-</sub> )		3 V	0.3	1	1.2	0.3	1.2	0.3	1.2	V
		4.5 V	0.4	1.2	1.4	0.4	1.4	0.4	1.4	
		5.5 V	0.5	1.4	1.6	0.5	1.6	0.5	1.6	
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	3 V			2.9	2.9		2.9		V
		4.5 V			4.4	4.4		4.4		
		5.5 V			5.4	5.4		5.4		
	I <sub>OH</sub> = -12 mA	3 V			2.56	2.4		2.48		
		4.5 V			3.86	3.7		3.8		
	I <sub>OH</sub> = -24 mA	4.5 V			3.86	3.7		3.8		
		5.5 V			4.86	4.7		4.8		
I <sub>OH</sub> = -50 mA <sup>(1)</sup>	5.5 V				3.85					
I <sub>OH</sub> = -75 mA <sup>(1)</sup>							3.85			
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	3 V			0.1	0.1		0.1		V
		4.5 V			0.1	0.1		0.1		
		5.5 V			0.1	0.1		0.1		
	I <sub>OL</sub> = 12 mA	3 V			0.36	0.44		0.44		
		4.5 V			0.36	0.44		0.44		
	I <sub>OL</sub> = 24 mA	4.5 V			0.36	0.44		0.44		
		5.5 V			0.36	0.44		0.44		
I <sub>OL</sub> = 50 mA <sup>(1)</sup>	5.5 V				1.65					
I <sub>OL</sub> = 75 mA <sup>(1)</sup>							1.65			
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V			±0.1	±1		±1		μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V			2	40		20		μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V			4.5					pF

(1) Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

## 5.6 Switching Characteristics

over recommended operating free-air temperature range, V<sub>CC</sub> = 3.3 V ± 0.3 V (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T <sub>A</sub> = 25°C			SN54AC14		SN74AC14		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A	Y	1.5	6	13.5	1	16	1.5	15	ns
t <sub>PHL</sub>			1.5	6	11.5	1	14	1.5	13	

## 5.7 Switching Characteristics

over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			SN54AC14		SN74AC14		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A	Y	1.5	5	10	1.5	12	1.5	11	ns
$t_{PHL}$			1.5	5	8.5	1.5	10	1.5	9.5	

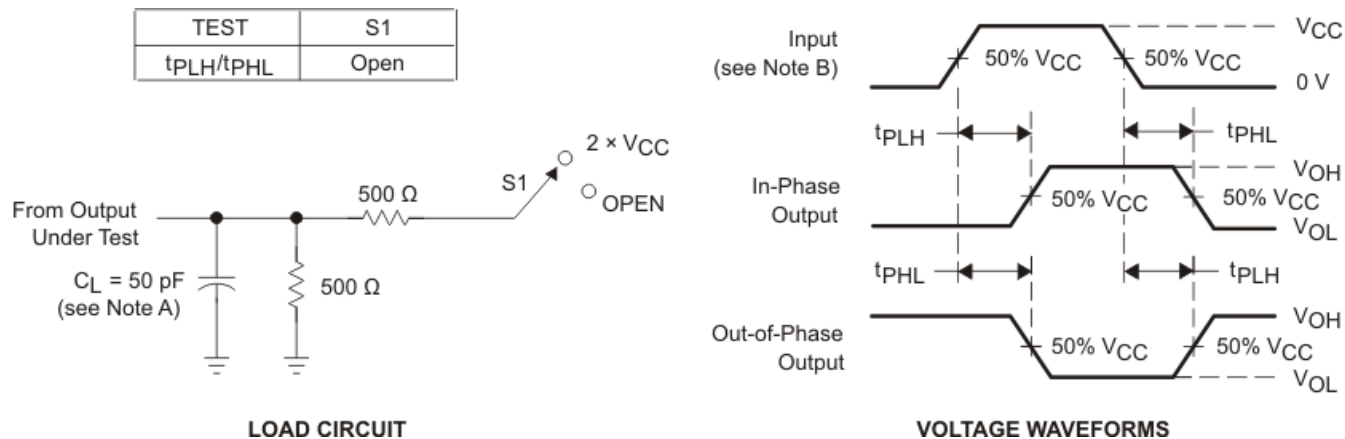
## 5.8 Operating Characteristics

$V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
$C_{pd}$	Power dissipation capacitance	$C_L = 50\text{ pF}$ , $f = 1\text{ MHz}$	25	pF

## 6 Parameter Measurement Information

### 6.1



- A.  $C_L$  includes probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5$  ns,  $t_f \leq 2.5$  ns.
- C. The outputs are measured one at a time with one input transition per measurement.

**Figure 6-1. Load Circuit and Voltage Waveforms**



## 7 Detailed Description

### 7.1 Overview

These 'AC14 devices perform the Boolean function  $Y = \bar{A}$ . Because of the Schmitt action, they have different input threshold levels for positive-going ( $V_{T+}$ ) and for negative-going ( $V_{T-}$ ) signals.

These circuits are temperature compensated and can be triggered from the slowest of input ramps and still give clean, jitter-free output signals. They also have a greater noise margin than conventional inverters.

### 7.2 Functional Block Diagram



### 7.3 Feature Description

- $V_{CC}$  is optimized at 5 V
- Allows up voltage translation from 3.3 V to 5 V
  - Inputs accept  $V_{IH}$  levels of 2 V
- Slow edge rates minimize output ringing
- Inputs are TTL-Voltage compatible

#### 7.3.1 Balanced CMOS Push-Pull Outputs

This device includes balanced CMOS push-pull outputs. The term *balanced* indicates that the device can sink and source similar currents. The drive capability of this device may create fast edges into light loads, so routing and load conditions should be considered to prevent ringing. Additionally, the outputs of this device are capable of driving larger currents than the device can sustain without being damaged. It is important to limit the output power of the device to avoid damage due to overcurrent. The electrical and thermal limits defined in the *Absolute Maximum Ratings* must be followed at all times.

Unused push-pull CMOS outputs must be left disconnected.

### 7.3.2 Clamp Diode Structure

As shown in Figure 7-1, the inputs and outputs to this device have both positive and negative clamping diodes.

**CAUTION**

Voltages beyond the values specified in the *Absolute Maximum Ratings* table can cause damage to the device. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

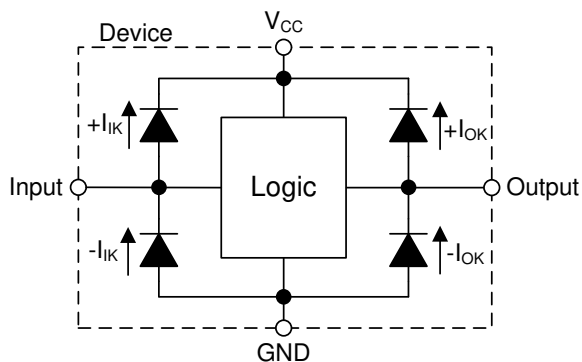


Figure 7-1. Electrical Placement of Clamping Diodes for Each Input and Output

### 7.4 Device Functional Modes

Table 7-1. Function Table

INPUT	OUTPUT
A	Y
H	L
L	H

## 8 Application Information Disclaimer

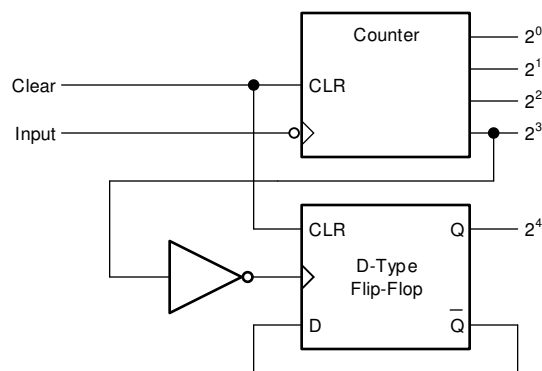
### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 8.1 Application Information

The SNx4AC14 device is a low-drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The inputs are tolerant to 5.5 V at any valid  $V_{CC}$ . This feature makes it ideal for translating down to the  $V_{CC}$  level. [Switching Characteristics Comparison](#) shows the reduction in ringing compared to higher drive parts such as AC.

### 8.2 Typical Application



**Figure 8-1. Typical Application Schematic**

#### 8.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads, so routing and load conditions should be considered to prevent ringing.

#### 8.2.2 Detailed Design Procedure

1. Recommended Input Conditions
  - For rise time and fall time specifications, see  $\Delta t/\Delta V$  in the [Section 5.3](#) table.
  - For specified High and low levels, see  $V_{IH}$  and  $V_{IL}$  in the [Section 5.3](#) table.
  - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid  $V_{CC}$ .
2. Recommend Output Conditions
  - Load currents should not exceed 35 mA per output and 70 mA total for the part.
  - Outputs should not be pulled above  $V_{CC}$ .

### 8.2.3 Application Curves

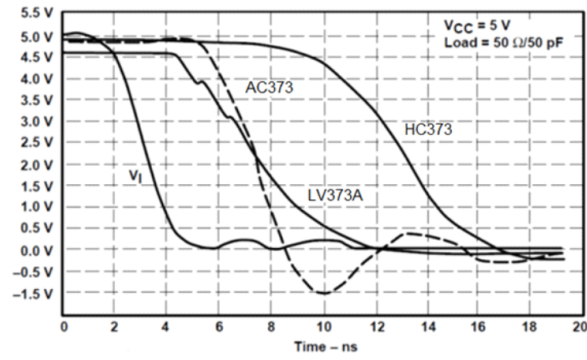


Figure 8-2. Switching Characteristics Comparison

### 8.3 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [Section 5.3](#).

Each  $V_{CC}$  pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1  $\mu\text{F}$  is recommended; if there are multiple  $V_{CC}$  pins, then 0.01  $\mu\text{F}$  or 0.022  $\mu\text{F}$  is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1  $\mu\text{F}$  and a 1  $\mu\text{F}$  are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

### 8.4 Layout

#### 8.4.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [Layout Diagram](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or  $V_{CC}$ , whichever makes more sense or is more convenient. It is acceptable to float outputs unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the outputs section of the part when asserted. This will not disable the input section of the I/Os so they also cannot float when disabled.

#### 8.4.2 Layout Example

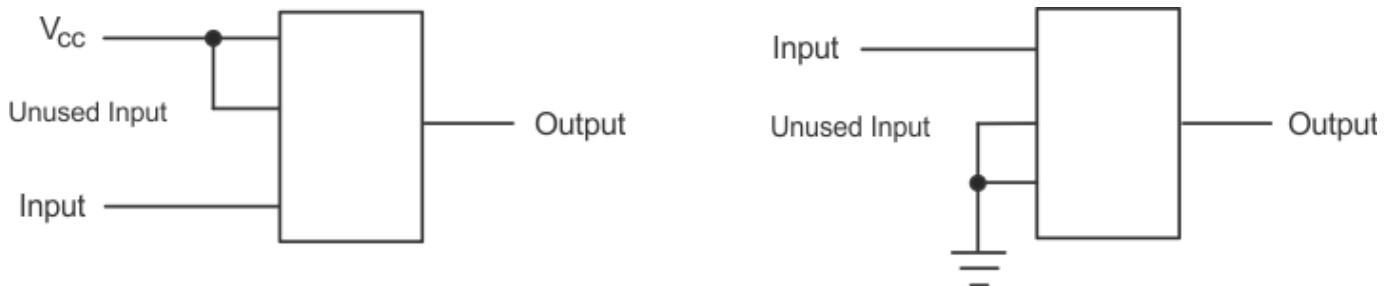


Figure 8-3. Layout Diagram

## 9 Device and Documentation Support

### 9.1 Documentation Support

#### 9.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 9-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN54AC14	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>
SN74AC14	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>

### 9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 9.3 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 9.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

### 9.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 9.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision H (January 2023) to Revision I (July 2024)	Page
• Added BQA package size to <i>Package Information</i> table, Pin Configuration and Functions section, and <i>Thermal Information</i> table.....	1
• Added package size to <i>Device Information</i> table.....	1
• Updated RθJA values: D = 86 to 89.9, DB = 96 to 101.2, N = 80 to 72.1, NS = 76 to 92.4, PW = 113 to 148, all values in °C/W.....	5

Changes from Revision G (August 2008) to Revision H (January 2023)	Page
• Added <i>Applications</i> , <i>Device Information</i> table, <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Typical Characteristics</i> , <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and</i>	

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*Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section..... 1*

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## **11 Mechanical, Packaging, and Orderable Information**

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-87624012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87624012A SNJ54AC 14FK	<a href="#">Samples</a>
5962-8762401CA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762401CA SNJ54AC14J	<a href="#">Samples</a>
5962-8762401DA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762401DA SNJ54AC14W	<a href="#">Samples</a>
5962-8762401VCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762401VC A SNV54AC14J	<a href="#">Samples</a>
5962-8762401VDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762401VD A SNV54AC14W	<a href="#">Samples</a>
5962-8762402VCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762402VC A SNV54AC14J	<a href="#">Samples</a>
5962-8762402VDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762402VD A SNV54AC14W	<a href="#">Samples</a>
SN74AC14BQAR	ACTIVE	WQFN	BQA	14	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AC14	<a href="#">Samples</a>
SN74AC14D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-40 to 85	AC14	
SN74AC14DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC14	<a href="#">Samples</a>
SN74AC14DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC14	<a href="#">Samples</a>
SN74AC14N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74AC14N	<a href="#">Samples</a>
SN74AC14NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC14	<a href="#">Samples</a>
SN74AC14NSRG4	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC14	<a href="#">Samples</a>
SN74AC14PW	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 85	AC14	
SN74AC14PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC14	<a href="#">Samples</a>



Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54AC14FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87624012A SNJ54AC 14FK	<a href="#">Samples</a>
SNJ54AC14J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762401CA SNJ54AC14J	<a href="#">Samples</a>
SNJ54AC14W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762401DA SNJ54AC14W	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54AC14, SN54AC14-SP, SN74AC14 :**

- Catalog : [SN74AC14](#), [SN54AC14](#)
  
- Automotive : [SN74AC14-Q1](#), [SN74AC14-Q1](#)
  
- Military : [SN54AC14](#)
  
- Space : [SN54AC14-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
  
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
  
- Military - QML certified for Military and Defense Applications
  
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC14BQAR	WQFN	BQA	14	3000	180.0	12.4	2.8	3.3	1.1	4.0	12.0	Q1
SN74AC14DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74AC14DR	SOIC	D	14	2500	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1
SN74AC14DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AC14DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AC14DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AC14NSR	SOP	NS	14	2000	330.0	16.4	8.45	10.55	2.5	12.0	16.2	Q1
SN74AC14NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AC14PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AC14PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC14BQAR	WQFN	BQA	14	3000	210.0	185.0	35.0
SN74AC14DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74AC14DR	SOIC	D	14	2500	340.5	336.1	32.0
SN74AC14DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74AC14DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74AC14DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74AC14NSR	SOP	NS	14	2000	353.0	353.0	32.0
SN74AC14NSR	SOP	NS	14	2000	356.0	356.0	35.0
SN74AC14PWR	TSSOP	PW	14	2000	353.0	353.0	32.0
SN74AC14PWR	TSSOP	PW	14	2000	356.0	356.0	35.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-87624012A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-8762401DA	W	CFP	14	25	506.98	26.16	6220	NA
5962-8762401VDA	W	CFP	14	25	506.98	26.16	6220	NA
5962-8762402VDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74AC14N	N	PDIP	14	25	506	13.97	11230	4.32
SN74AC14N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54AC14FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54AC14W	W	CFP	14	25	506.98	26.16	6220	NA



# D0014A

# PACKAGE OUTLINE

## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

# EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



## GENERIC PACKAGE VIEW

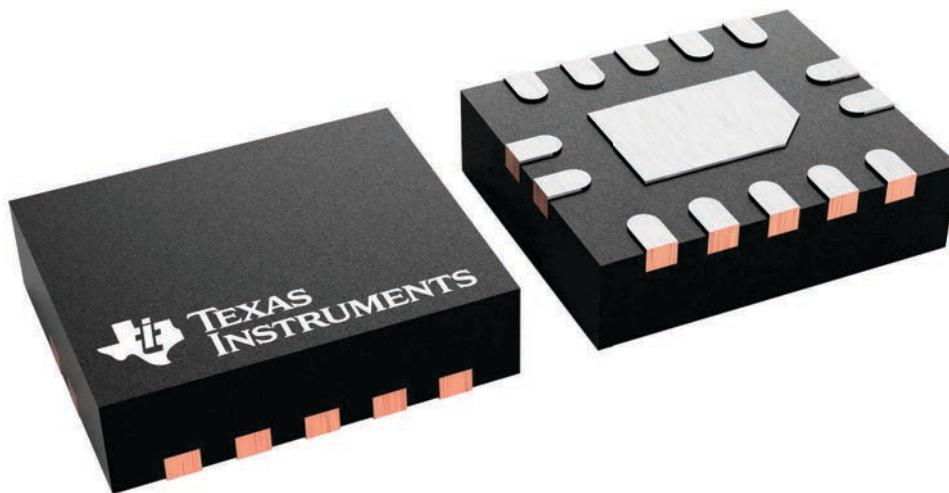
**BQA 14**

**WQFN - 0.8 mm max height**

2.5 x 3, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4227145/A



4224636/A 11/2018

**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

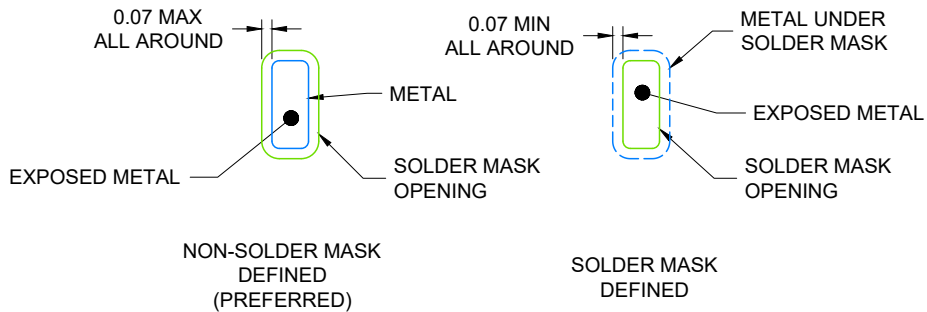
WQFN - 0.8 mm max height

BQA0014A

PLASTIC QUAD FLAT PACK-NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 20X



4224636/A 11/2018

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

BQA0014A

WQFN - 0.8 mm max height

PLASTIC QUAD FLAT PACK-NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD  
88% PRINTED COVERAGE BY AREA  
SCALE: 20X

4224636/A 11/2018

NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14

# DB0014A



# PACKAGE OUTLINE

## SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220762/A 05/2024

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# EXAMPLE STENCIL DESIGN

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

**FK 20**

**LCCC - 2.03 mm max height**

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4229370VA\

J 14

**GENERIC PACKAGE VIEW**  
**CDIP - 5.08 mm max height**  
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

J0014A



# PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



4214771/A 05/2017

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

PW0014A



**PACKAGE OUTLINE**  
**TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



4220202/B 12/2023

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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